



VMDSEMI

VUPA002R070NA

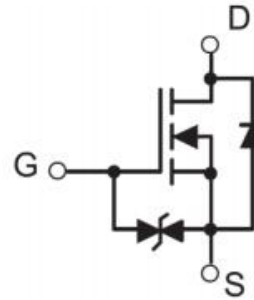
Datasheet



VMDSEMI

General Description
Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	I_D
20V	7.0mΩ@4.5V	10A
	9.0mΩ@2.5V	



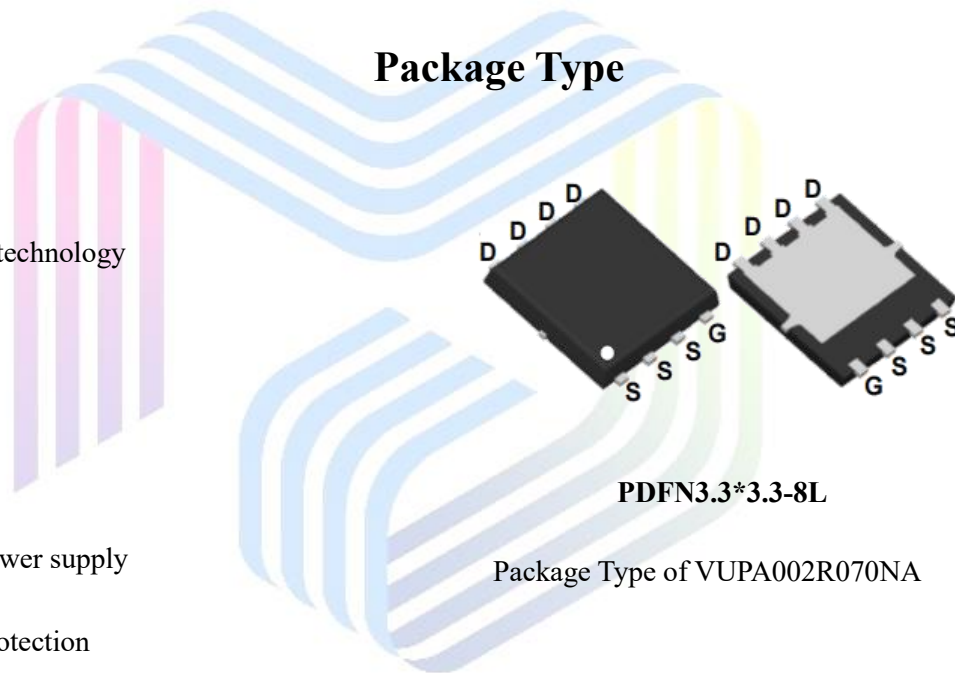
Symbol of VUPA002R070NA

Features

- Low $R_{DS(ON)}$
- Advanced Trench technology
- ESD Protected
- Low gate charge

Application

- BMS
- Switched mode power supply
- DC-DC converter
- Lithium battery protection

Package Type

PDFN3.3*3.3-8L

Package Type of VUPA002R070NA

Ordering Information

Product Name	Package
VUPA002R070NA	PDFN3.3*3.3-8L

Absolute Maximum Ratings ($T_A=25\text{ }^\circ\text{C}$, unless otherwise specified)

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V_{DS}	20	V
Gate-Source Voltage		V_{GS}	± 12	V
Continuous Drain Current ^{Note 1}	$T_C=25^\circ\text{C}$	I_D	20	A
Pulsed Drain Current ^{Note 2}	$T_C=25^\circ\text{C}$	I_{DM}	60	A
Max Power Dissipation ^{Note 3}	$T_C=25^\circ\text{C}$	P_D	3	W
Avalanche Energy, Single Pulse ^{Note 4}		E_{AS}	53	mJ
Operation Junction temperature		T_J	-55 to 150	$^\circ\text{C}$

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient ^{Note 5}	$R_{\theta JA}$	-	42	-	$^\circ\text{C/W}$

Notes:

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_D is based on max. junction temperature, using junction-case thermal resistance.
- 4) $V_{DS}=10\text{V}, V_{GS}=10\text{V}, L=0.5\text{mH}$, starting $T_J=25\text{ }^\circ\text{C}$.
- 5) The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_A=25\text{ }^\circ\text{C}$.

Electrical Characteristics($T_J=25\text{ }^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	20	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=60V, V_{GS}=0V$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 12V, V_{DS}=0V$	-	-	± 5	μA
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.4	0.7	1.0	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=4.5V, I_D=10A$	-	5.2	7	$m\Omega$
		$V_{GS}=2.5V, I_D=10A$	-	6.3	9	
Gate Resistance	R_G	$f=1MHz, \text{Open Drain}$	-	4.7	-	Ω
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{GS}=0V$	-	1472	-	pF
Output Capacitance	C_{OSS}	$V_{DS}=10V$	-	192	-	pF
Reverse Transfer Capacitance	C_{RSS}	$f=1MHz$	-	183	-	pF
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=10V$	-	10.3	-	ns
Rise Time	t_r	$V_{GS}=10V$	-	7.1	-	
Turn-off Delay Time	$t_{d(off)}$	$R_L=1.2\Omega$	-	25.6	-	
Fall Time	t_f	$R_G=3\Omega$	-	22.8	-	
Switching Characteristics						
Total Gate Charge	Q_g	$V_{GS}=4.5V$	-	13.8	-	nC
Gate to Source Charge	Q_{gs}	$V_{DS}=10V$	-	2.2	-	
Gate to Drain Charge	Q_{gd}	$I_D=8A$	-	3.7	-	
Reverse Diode Characteristics						
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_{SD}=10A$	-	0.7	1.2	V

Typical Performance Characteristics

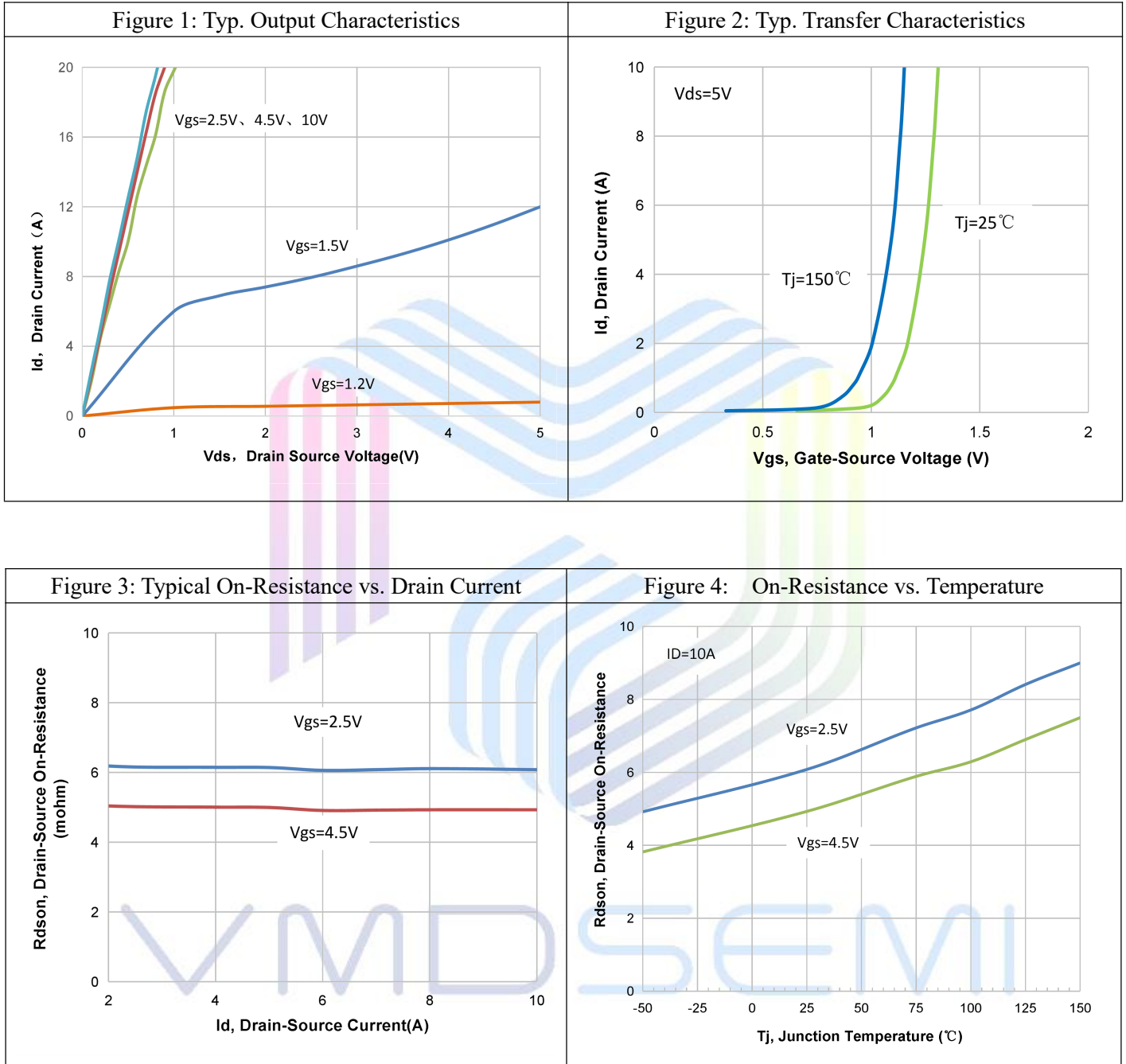
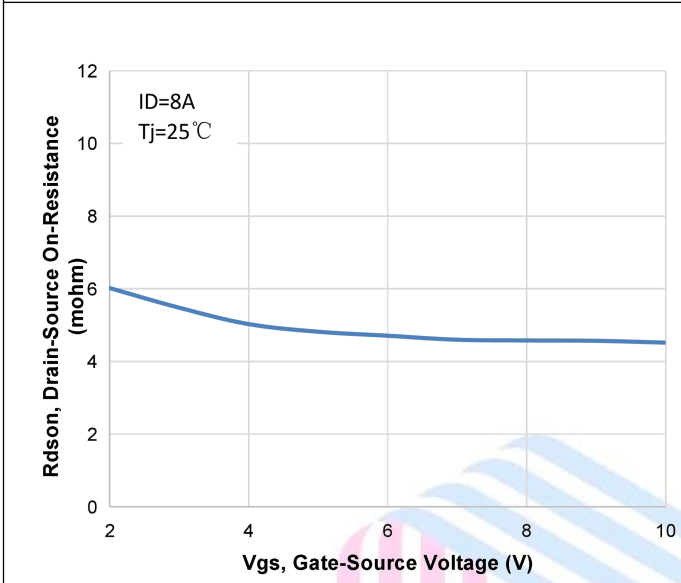
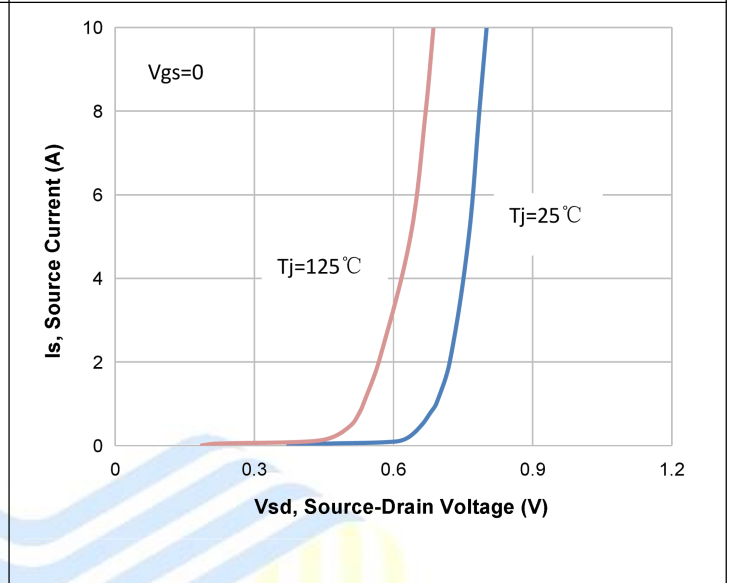
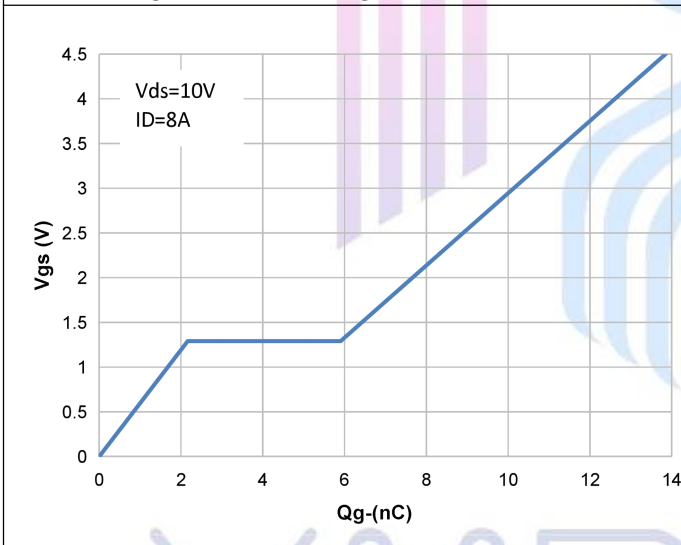
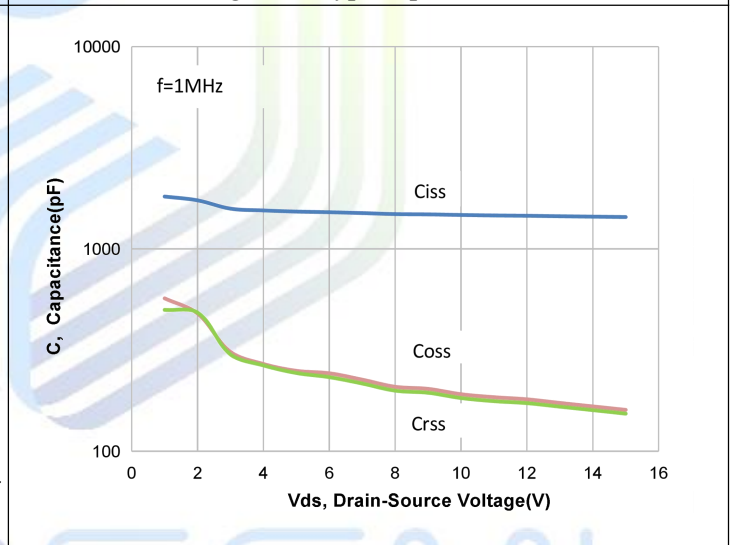
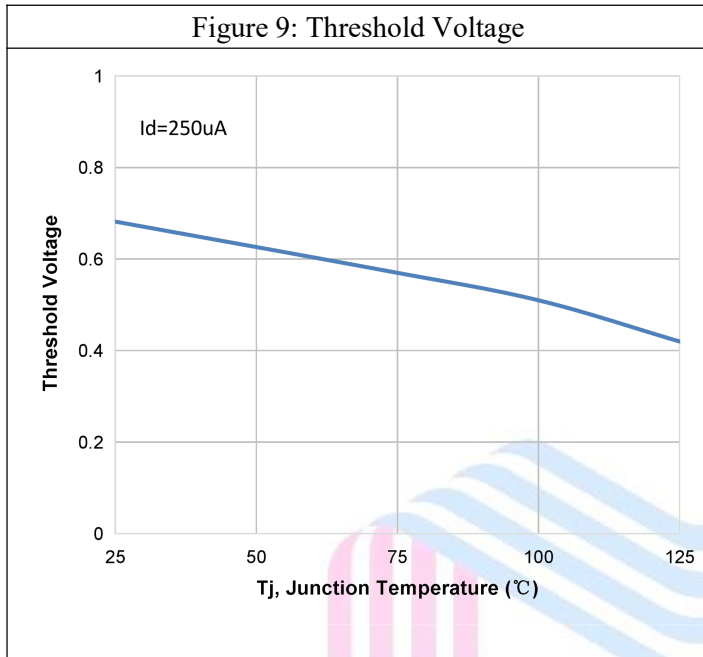


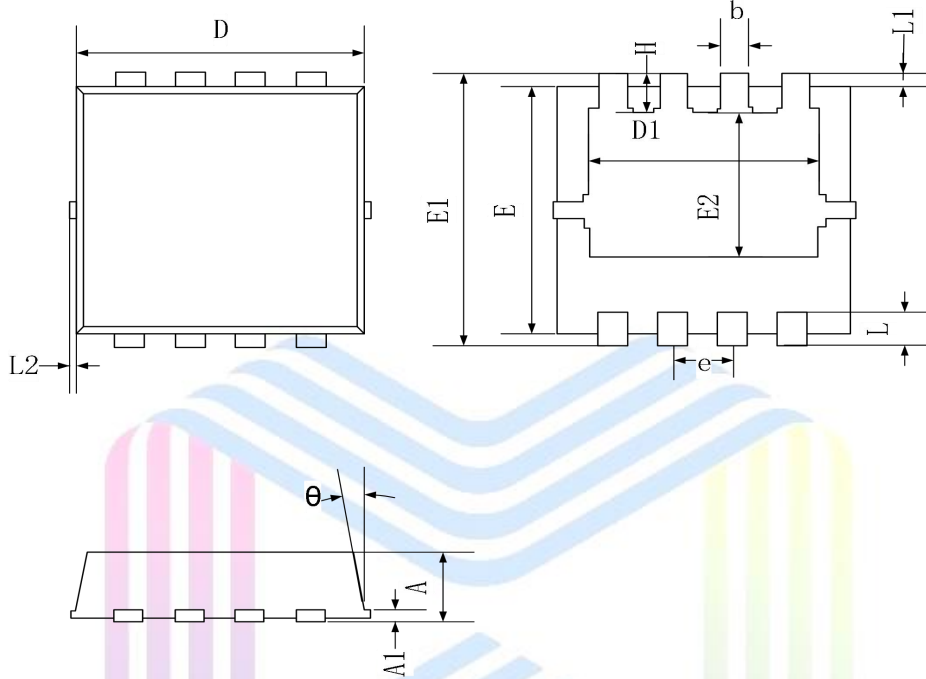
Figure 5: On-Resistance vs. Gate-source voltage

Figure 6: Forward Characteristics of Body Diode

Figure 7: Gate Charge Characteristics

Figure 8: Typ. Capacitances




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Mechanical Dimensions

PDFN3.3*3.3-8L Package Information



SYMBOL	MILLIMETERS	
	MIN	MAX
A	0.70	0.90
A1	0.10	0.25
D	2.90	3.25
D1	2.25	2.69
E	2.90	3.20
E1	3.00	3.60
E2	1.35	2.20
b	0.20	0.40
e	0.65BSC	
L	0.30	0.50
L1	0.13BSC	
L2	0.00	0.20
H	0.15	0.65
θ	0°	14°

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